



SOT684-26

HVQFN56, thermal enhanced very thin quad flat package, no leads, 56 terminals, 0.5 mm pitch, 8 mm x 8 mm x 0.85 mm body

25 May 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-03-2020
Manufacturer package code	98ASA01581D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.9	8	8.1	mm
package width	7.9	8	8.1	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	56	-	



HVQFN56, thermal enhanced very thin quad flat package, no leads, 56 terminals, 0.5 mm pitch, 8 mm x 8 mm x 0.85 mm body

2 Package outline

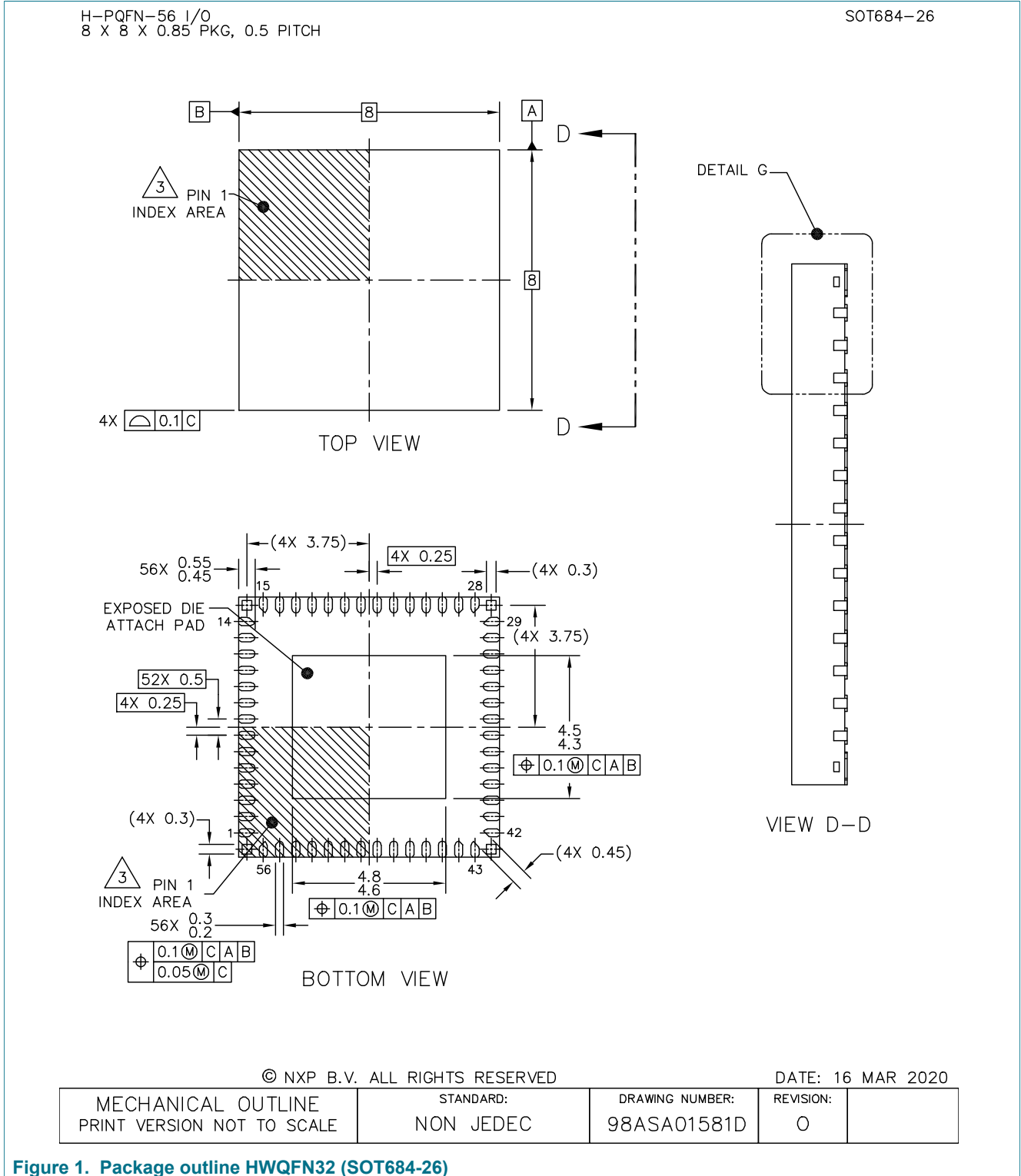
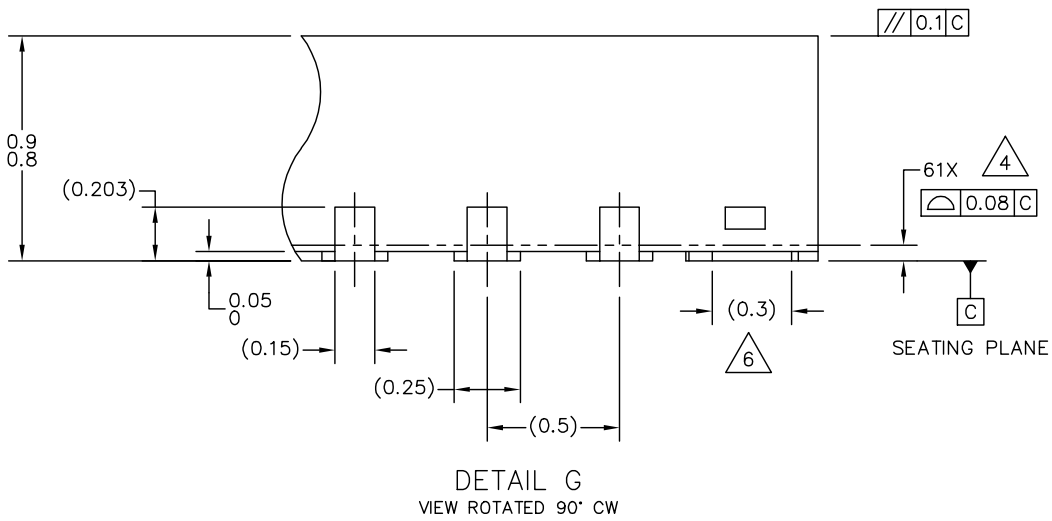


Figure 1. Package outline HWQFN32 (SOT684-26)

HVQFN56, thermal enhanced very thin quad flat package, no leads, 56 terminals, 0.5 mm pitch, 8 mm x 8 mm x 0.85 mm body

H-PQFN-56 I/O
8 X 8 X 0.85 PKG, 0.5 PITCH

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Figure 2. Package outline detail HWQFN32 (SOT684-26)

3 Soldering

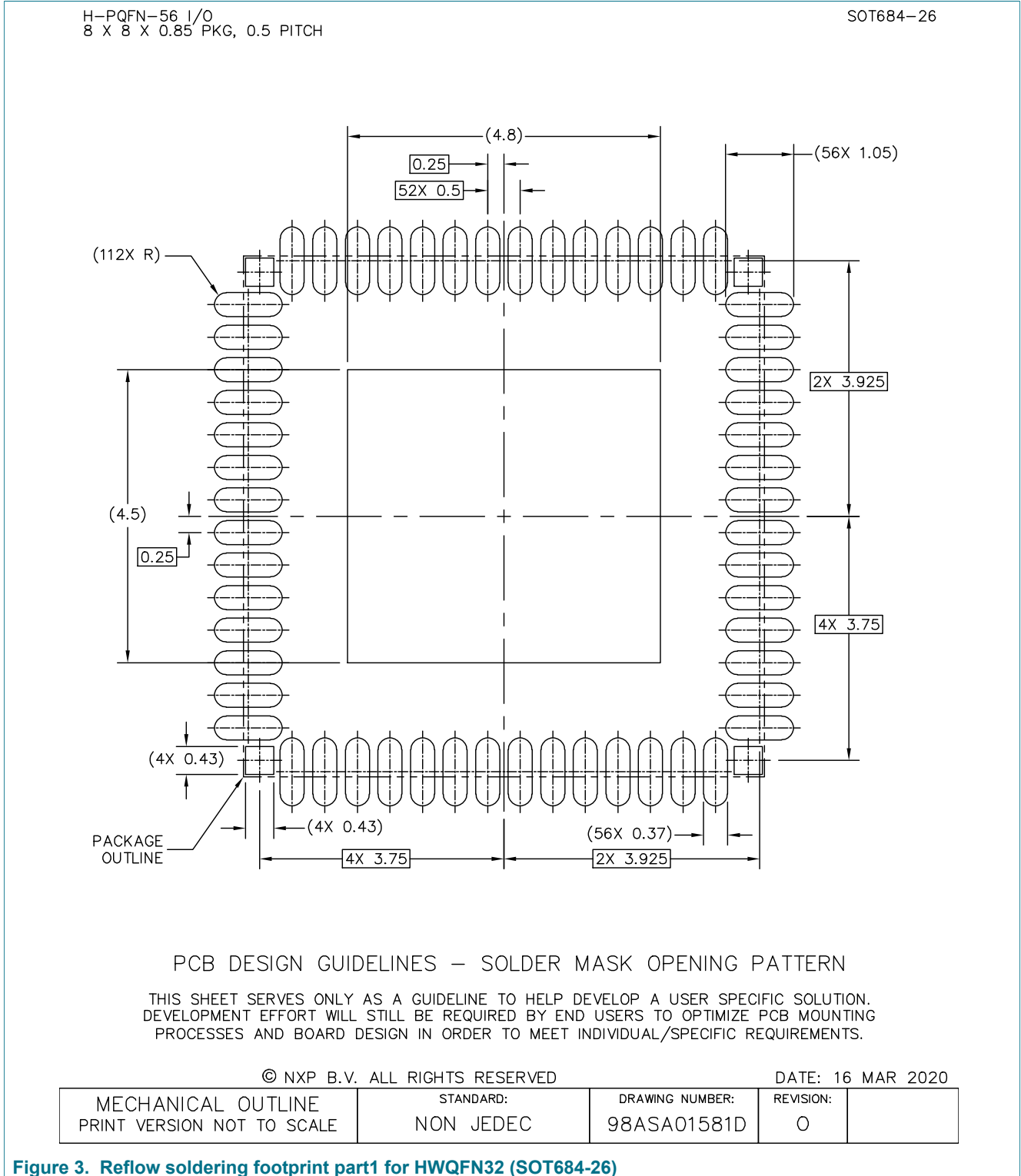
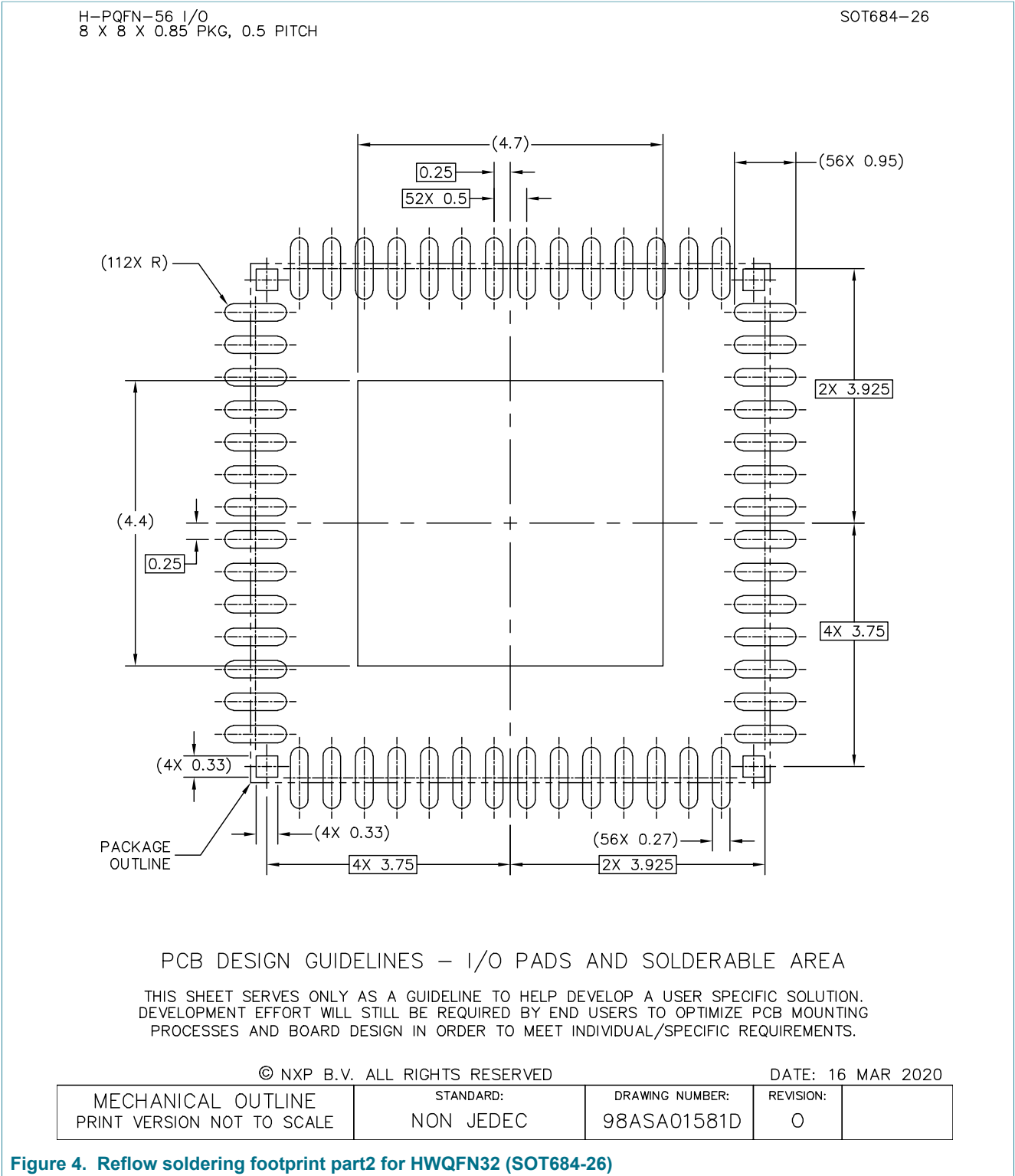


Figure 3. Reflow soldering footprint part1 for HWQFN32 (SOT684-26)

HVQFN56, thermal enhanced very thin quad flat package, no leads, 56 terminals, 0.5 mm pitch, 8 mm x 8 mm x 0.85 mm body



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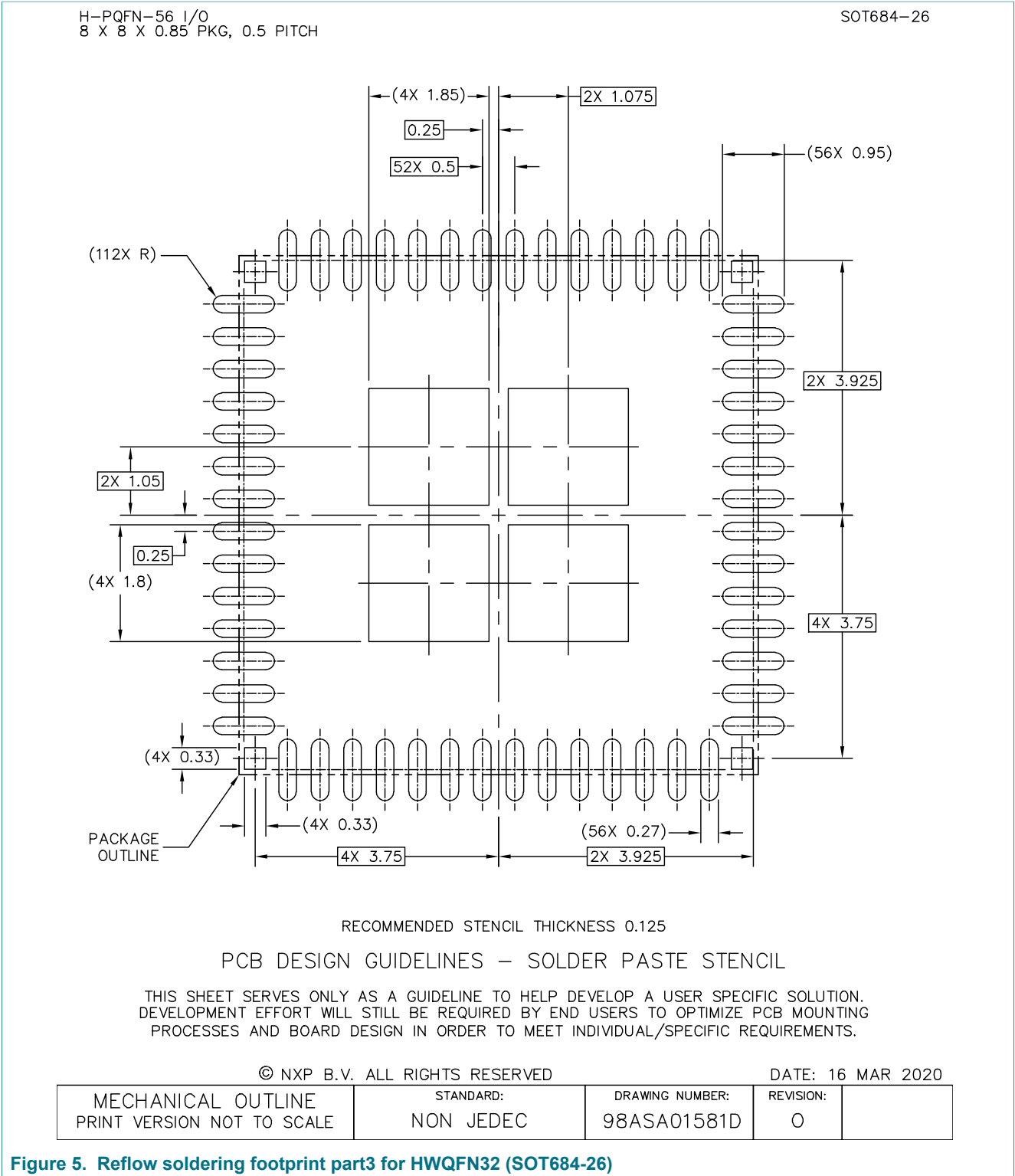


Figure 5. Reflow soldering footprint part3 for HWQFN32 (SOT684-26)

HVQFN56, thermal enhanced very thin quad flat package, no leads, 56 terminals, 0.5 mm pitch, 8 mm x 8 mm x 0.85 mm body

H-PQFN-56 I/O
8 X 8 X 0.85 PKG, 0.5 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
6. ANCHORING PADS.

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Figure 6. Package outline note HWQFN32 (SOT684-26)

4 Legal information

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